Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7875	((438/106) or (438/110) or (438/113) or (438/114) or (438/460) or (438/461) or (438/462) or (438/463) or (438/465) or (438/660) or (438/662)).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/10/26 13:37
L2	7875	L1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 13:37
L3	1012	438/462.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 13:40
L4	390	438/114.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 13:41
L5	1328	438/460.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 13:41
L6	1446	438/113.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 13:41
L7	292	438/463.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 13:41

L8	2	"20070287267"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/26 14:01
S1	2	"20070086832"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2007/11/28 12:07
S2	7114	((438/106) or (438/110) or (438/113) or (438/114) or (438/460) or (438/461) or (438/462) or (438/463) or (438/465) or (438/660) or (438/662)).CCLS.	US-PGPUB; USPAT	OR	OFF	2007/11/28 12:09
S3	65026	laser same irradiation	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2007/11/28 12:09
S4	351877	laminate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2007/11/28 12:09
S5	74653	functional same devices	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2007/11/28 12:10
S6	143	light\$1converg\$3 same point	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2007/11/28 12:11

S7	91281	modified same region	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2007/11/28 12:11
S8	6995371	cut\$4 or block or dic\$3 or chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 12:12
S9	10	exand\$4 with film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 12:13
S10	7609	molten same process\$3 same region	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 12:23
S11	6145422	laminate or layer or film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 12:24
S12	745	S3 and S11 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 13:59
S13	11	S2 and S12	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 12:27

S14	0	S12 and S8 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 14:00
S15	27761	expand\$4 with film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 14:01
S16	6	S3 and S5 and S7 and S8 and S11 and S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 14:03
S17	1801	S5 and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 14:05
S18	6	S2 and S17	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 14:27
S19	2	"20050272223"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/11/28 14:27
S20	1	("20040002199").PN.	US-PGPUB; USPAT	OR	OFF	2008/10/23 15:15
S21	1	("20050272223").PN.	US-PGPUB; USPAT	OR	OFF	2008/10/23 15:16

S22	85882	functional same devices	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/23 15:20
S23	101598	modified same region	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/10/23 15:20
S24	2097	S22 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/10/23 15:20
S25	5	"03077295"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/10/23 15:21
S26	2	modified with region with line with cut with chip with laser with light with converg\$4.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/10/23 16:00
S27	0	modified with region with line with cut with chip with laser with light with converg\$4 with fracture.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/10/23 16:10
S28	0	modified with region with line with cut with chip with laser with light with converg\$4 with light with blocks.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/10/23 16:10

S29	0	modified with region with substrate with first with line with cut with laminate with block with chip.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO;	OR	ON	2008/10/23 16:14
			DERWENT; IBM_TDB			

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